

ABSTRACT OF THE DISCLOSURE

The present invention solves a problem that in a wire bonding process, an inert gas used for prevention of oxidation of a substrate gave rise to shimmer due to the temperature difference during bonding, thereby degrading the precision of pattern recognition. With this invention's bonding device 21 provided with recognition device, a shimmer prevention blow mechanism 31 is disposed between a ring illumination 25 and a working hole 24 and near working hole 24. Though the nitrogen gas that blows out from working hole 24 gives rise to shimmer due to temperature difference, this shimmer can be blown away by the nitrogen gas blow from shimmer prevention blow mechanism 31. As a result, the recognition precision of a recognition camera can be improved and the wire bonding precision of the μm order can be improved.